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Details

Product Status	Active
Core Processor	RX
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I ² C, SCI, SPI, USB OTG
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	46
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	8K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 14x12b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LFQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f5111jadfm-3a

1.5 Pin Assignments

Figure 1.3 to Figure 1.7 show the pin assignments. Table 1.5 to Table 1.9 show the lists of pins and pin functions.

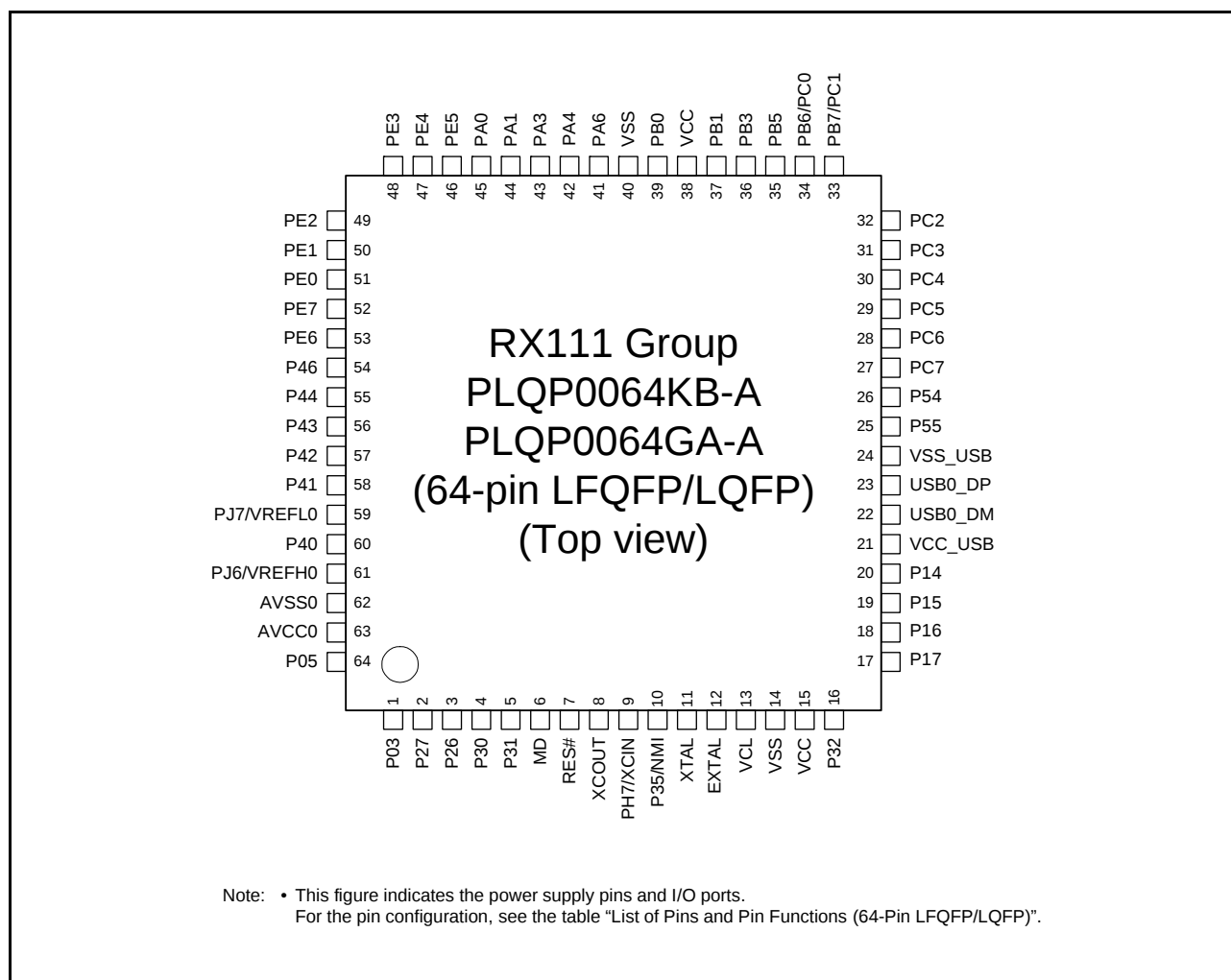


Figure 1.3 Pin Assignments of the 64-Pin LFQFP/LQFP

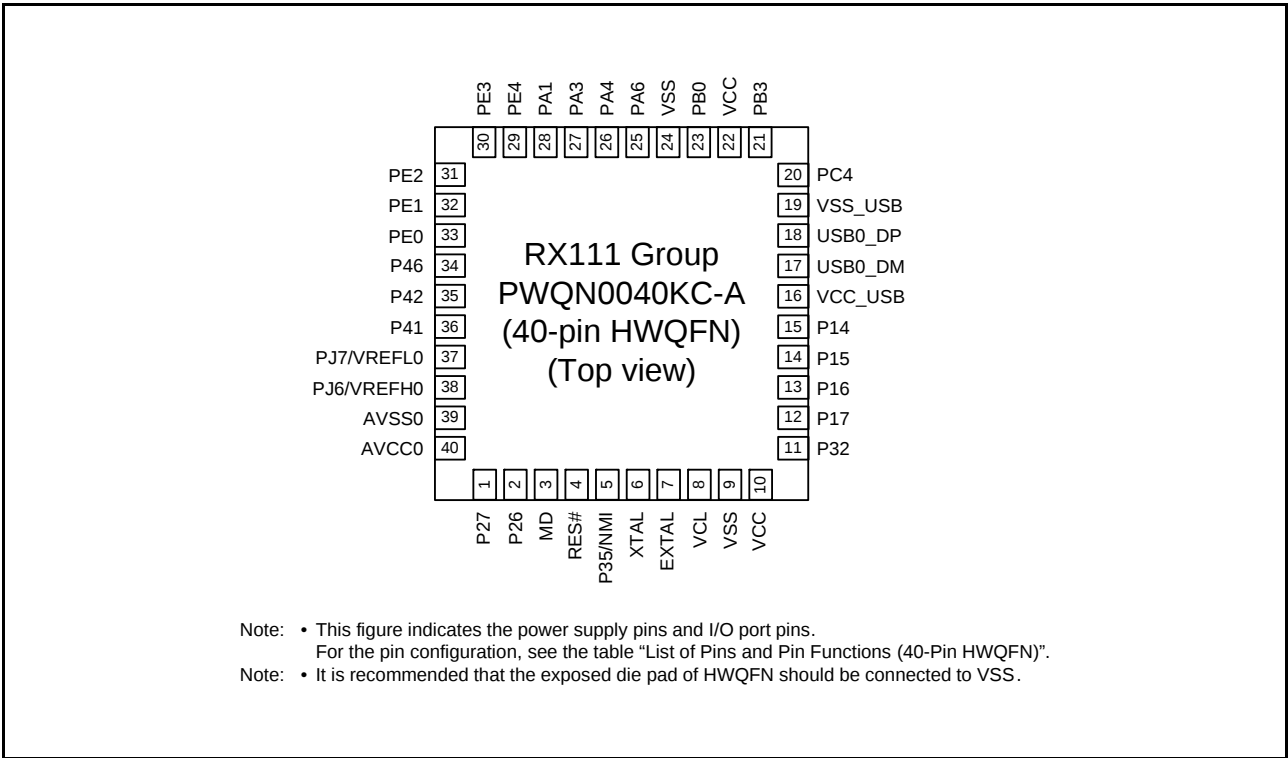
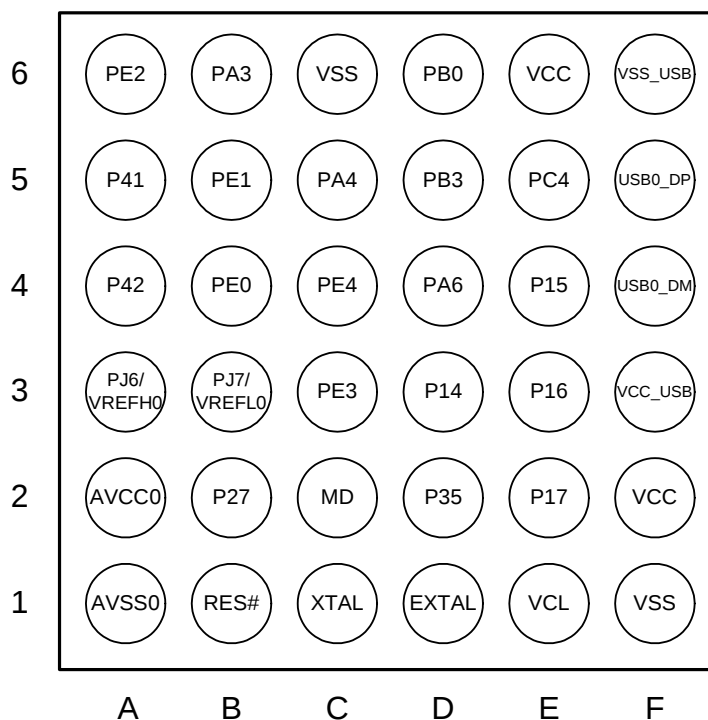


Figure 1.6 Pin Assignments of the 40-Pin HWQFN

RX111 Group
PWLG0036KA-A
(36-pin WFLGA)
(Upper perspective view)



Note:

- This figure indicates the power supply pins and I/O port pins. For the pin configuration, see the table "List of Pins and Pin Functions (36-Pin WFLGA)".
- For the position of A1 pin in the package, see "Package Dimensions".

Figure 1.7 Pin Assignments of the 36-Pin WFLGA

Table 1.8 List of Pins and Pin Functions (40-Pin HWQFN) (1/2)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, POE, RTC)	Communication (SCle, SCIf, RSPI, RIIC, USB)	Others
1		P27	MTIOC2B	SCK1/SCK12	IRQ3/CMPA2/CACREF/ADTRG0#
2		P26	MTIOC2A	TXD1/SMOSI1/SSDA1/USB0_VBUSEN	
3	MD				FINED
4	RES#				
5	UPSEL	P35			NMI
6	XTAL				
7	EXTAL				
8	VCL				
9	VSS				
10	VCC				
11		P32	MTIOC0C		IRQ2
12		P17	MTIOC0C/MTIOC3A/MTIOC3B/POE8#	SCK1/MISOA/SDA0/RXD12/RXD12/SMISO12/SSCL12	IRQ7
13		P16	MTIOC3C/MTIOC3D	TXD1/SMOSI1/SSDA1/SCL0/MOSIA/USB0_VBUSEN/USB0_OVRCURB/USB0_VBUS	IRQ6/ADTRG0#
14		P15	MTIOC0B/MTCLKB	RXD1/SMISO1/SSCL1/RSPCKA	IRQ5/CLKOUT
15	UB#	P14	MTIOC0A/MTIOC3A/MTCLKA	CTS1#/RTS1#/SS1#/SSLA0/TXD12/TXD12/SIOX12/SMOSI12/SSDA12/USB0_OVRCURA	IRQ4
16	VCC_USB				
17				USB0_DM	
18				USB0_DP	
19	VSS_USB				
20		PC4	MTIOC3D/MTCLKC/POE0#	SCK5/SSLA0/USB0_VBUS*1/USB0_VBUSEN	IRQ2/CLKOUT
21		PB3	MTIOC0A/MTIOC3B/MTIOC4A/POE3#	USB0_OVRCURA	
22	VCC				
23		PB0	MTIOC0C/MTIC5W	SCL0/RSPCKA	IRQ2/ADTRG0#
24	VSS				
25		PA6	MTIOC2A/MTIC5V/MTCLKB/POE2#	CTS5#/RTS5#/SS5#/SDA0/MOSIA	IRQ3
26		PA4	MTIOC2B/MTIC5U/MTCLKA	TXD5/SMOSI5/SSDA5/SSLA0	IRQ5
27		PA3	MTIOC0D/MTIOC1B/MTCLKD/POE0#	RXD5/SMISO5/SSCL5/MISOA	IRQ6
28		PA1	MTIOC0B/MTCLKC	SCK5/SSLA2	
29		PE4	MTIOC1A/MTIOC3A/MTIOC4D	MOSIA	IRQ4/AN012
30		PE3	MTIOC0A/MTIOC1B/MTIOC4B/POE8#	CTS12#/RTS12#/SS12#/RSPCKA	IRQ3/AN011
31		PE2	MTIOC4A	RXD12/RXD12/SMISO12/SSCL12	IRQ7/AN010
32		PE1	MTIOC4C	TXD12/TXD12/SIOX12/SMOSI12/SSDA12	IRQ1/AN009
33		PE0	MTIOC2A/POE3#	SCK12	IRQ0/AN008
34		P46*2			AN006
35		P42*2			AN002
36		P41*2			AN001
37	VREFL0	PJ7*2			
38	VREFH0	PJ6*2			
39	AVSS0				

Table 4.1 List of I/O Registers (Address Order) (6/16)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
0008 7594h	ICU	NMI Pin Digital Filter Setting Register	NMIFLTC	8	8	2 ICLK
0008 8000h	CMT	Compare Match Timer Start Register 0	CMSTR0	16	16	2 or 3 PCLKB
0008 8002h	CMT0	Compare Match Timer Control Register	CMCR	16	16	2 or 3 PCLKB
0008 8004h	CMT0	Compare Match Timer Counter	CMCNT	16	16	2 or 3 PCLKB
0008 8006h	CMT0	Compare Match Timer Constant Register	CMCOR	16	16	2 or 3 PCLKB
0008 8008h	CMT1	Compare Match Timer Control Register	CMCR	16	16	2 or 3 PCLKB
0008 800Ah	CMT1	Compare Match Timer Counter	CMCNT	16	16	2 or 3 PCLKB
0008 800Ch	CMT1	Compare Match Timer Constant Register	CMCOR	16	16	2 or 3 PCLKB
0008 8030h	IWDT	IWDT Refresh Register	IWDTRR	8	8	2 or 3 PCLKB
0008 8032h	IWDT	IWDT Control Register	IWDTCR	16	16	2 or 3 PCLKB
0008 8034h	IWDT	IWDT Status Register	IWDTSR	16	16	2 or 3 PCLKB
0008 8036h	IWDT	IWDT Reset Control Register	IWDTRCR	8	8	2 or 3 PCLKB
0008 8038h	IWDT	IWDT Count Stop Control Register	IWDCSTPR	8	8	2 or 3 PCLKB
0008 80C0h	DA	D/A Data Register 0	DADR0	16	16	2 or 3 PCLKB
0008 80C2h	DA	D/A Data Register 1	DADR1	16	16	2 or 3 PCLKB
0008 80C4h	DA	D/A Control Register	DACR	8	8	2 or 3 PCLKB
0008 80C5h	DA	DADRM Format Select Register	DADPR	8	8	2 or 3 PCLKB
0008 8280h	CRC	CRC Control Register	CRCCR	8	8	2 or 3 PCLKB
0008 8281h	CRC	CRC Data Input Register	CRCDIR	8	8	2 or 3 PCLKB
0008 8282h	CRC	CRC Data Output Register	CRCDOR	16	16	2 or 3 PCLKB
0008 8300h	RIIC0	I ² C Bus Control Register 1	ICCR1	8	8	2 or 3 PCLKB
0008 8301h	RIIC0	I ² C Bus Control Register 2	ICCR2	8	8	2 or 3 PCLKB
0008 8302h	RIIC0	I ² C Bus Mode Register 1	ICMR1	8	8	2 or 3 PCLKB
0008 8303h	RIIC0	I ² C Bus Mode Register 2	ICMR2	8	8	2 or 3 PCLKB
0008 8304h	RIIC0	I ² C Bus Mode Register 3	ICMR3	8	8	2 or 3 PCLKB
0008 8305h	RIIC0	I ² C Bus Function Enable Register	ICFER	8	8	2 or 3 PCLKB
0008 8306h	RIIC0	I ² C Bus Status Enable Register	ICSER	8	8	2 or 3 PCLKB
0008 8307h	RIIC0	I ² C Bus Interrupt Enable Register	ICIER	8	8	2 or 3 PCLKB
0008 8308h	RIIC0	I ² C Bus Status Register 1	ICSR1	8	8	2 or 3 PCLKB
0008 8309h	RIIC0	I ² C Bus Status Register 2	ICSR2	8	8	2 or 3 PCLKB
0008 830Ah	RIIC0	Slave Address Register L0	SARL0	8	8	2 or 3 PCLKB
0008 830Ah	RIIC0	Timeout Internal Counter L	TMOCNTL	8	8	2 or 3 PCLKB
0008 830Bh	RIIC0	Slave Address Register U0	SARU0	8	8	2 or 3 PCLKB
0008 830Bh	RIIC0	Timeout Internal Counter U	TMOCNTU	8	8 *1	2 or 3 PCLKB
0008 830Ch	RIIC0	Slave Address Register L1	SARL1	8	8	2 or 3 PCLKB
0008 830Dh	RIIC0	Slave Address Register U1	SARU1	8	8	2 or 3 PCLKB
0008 830Eh	RIIC0	Slave Address Register L2	SARL2	8	8	2 or 3 PCLKB
0008 830Fh	RIIC0	Slave Address Register U2	SARU2	8	8	2 or 3 PCLKB
0008 8310h	RIIC0	I ² C Bus Bit Rate Low-Level Register	ICBRL	8	8	2 or 3 PCLKB
0008 8311h	RIIC0	I ² C Bus Bit Rate High-Level Register	ICBRH	8	8	2 or 3 PCLKB
0008 8312h	RIIC0	I ² C Bus Transmit Data Register	ICDRT	8	8	2 or 3 PCLKB
0008 8313h	RIIC0	I ² C Bus Receive Data Register	ICDRR	8	8	2 or 3 PCLKB
0008 8380h	RSPI0	RSPI Control Register	SPCR	8	8	2 or 3 PCLKB
0008 8381h	RSPI0	RSPI Slave Select Polarity Register	SSLP	8	8	2 or 3 PCLKB
0008 8382h	RSPI0	RSPI Pin Control Register	SPPCR	8	8	2 or 3 PCLKB
0008 8383h	RSPI0	RSPI Status Register	SPSR	8	8	2 or 3 PCLKB
0008 8384h	RSPI0	RSPI Data Register	SPDR	32	16, 32	2 or 3 PCLKB/2ICLK
0008 8388h	RSPI0	RSPI Sequence Control Register	SPSCR	8	8	2 or 3 PCLKB
0008 8389h	RSPI0	RSPI Sequence Status Register	SPSSR	8	8	2 or 3 PCLKB
0008 838Ah	RSPI0	RSPI Bit Rate Register	SPBR	8	8	2 or 3 PCLKB
0008 838Bh	RSPI0	RSPI Data Control Register	SPDCR	8	8	2 or 3 PCLKB
0008 838Ch	RSPI0	RSPI Clock Delay Register	SPCKD	8	8	2 or 3 PCLKB

Table 4.1 List of I/O Registers (Address Order) (11/16)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
0008 B127h	ELC	Port Buffer Register 1	PDBF1	8	8	2 or 3 PCLKB
0008 B129h	ELC	Event Link Port Setting Register 0	PEL0	8	8	2 or 3 PCLKB
0008 B12Ah	ELC	Event Link Port Setting Register 1	PEL1	8	8	2 or 3 PCLKB
0008 B12Dh	ELC	Event Link Software Event Generation Register	ELSEGR	8	8	2 or 3 PCLKB
0008 B300h	SCI12	Serial Mode Register	SMR	8	8	2 or 3 PCLKB
0008 B301h	SCI12	Bit Rate Register	BRR	8	8	2 or 3 PCLKB
0008 B302h	SCI12	Serial Control Register	SCR	8	8	2 or 3 PCLKB
0008 B303h	SCI12	Transmit Data Register	TDR	8	8	2 or 3 PCLKB
0008 B304h	SCI12	Serial Status Register	SSR	8	8	2 or 3 PCLKB
0008 B305h	SCI12	Receive Data Register	RDR	8	8	2 or 3 PCLKB
0008 B306h	SCI12	Smart Card Mode Register	SCMR	8	8	2 or 3 PCLKB
0008 B307h	SCI12	Serial Extended Mode Register	SEMR	8	8	2 or 3 PCLKB
0008 B308h	SCI12	Noise Filter Setting Register	SNFR	8	8	2 or 3 PCLKB
0008 B309h	SCI12	I ² C Mode Register 1	SIMR1	8	8	2 or 3 PCLKB
0008 B30Ah	SCI12	I ² C Mode Register 2	SIMR2	8	8	2 or 3 PCLKB
0008 B30Bh	SCI12	I ² C Mode Register 3	SIMR3	8	8	2 or 3 PCLKB
0008 B30Ch	SCI12	I ² C Status Register	SISR	8	8	2 or 3 PCLKB
0008 B30Dh	SCI12	SPI Mode Register	SPMR	8	8	2 or 3 PCLKB
0008 B320h	SCI12	Extended Serial Mode Enable Register	ESMER	8	8	2 or 3 PCLKB
0008 B321h	SCI12	Control Register 0	CR0	8	8	2 or 3 PCLKB
0008 B322h	SCI12	Control Register 1	CR1	8	8	2 or 3 PCLKB
0008 B323h	SCI12	Control Register 2	CR2	8	8	2 or 3 PCLKB
0008 B324h	SCI12	Control Register 3	CR3	8	8	2 or 3 PCLKB
0008 B325h	SCI12	Port Control Register	PCR	8	8	2 or 3 PCLKB
0008 B326h	SCI12	Interrupt Control Register	ICR	8	8	2 or 3 PCLKB
0008 B327h	SCI12	Status Register	STR	8	8	2 or 3 PCLKB
0008 B328h	SCI12	Status Clear Register	STCR	8	8	2 or 3 PCLKB
0008 B329h	SCI12	Control Field 0 Data Register	CF0DR	8	8	2 or 3 PCLKB
0008 B32Ah	SCI12	Control Field 0 Compare Enable Register	CF0CR	8	8	2 or 3 PCLKB
0008 B32Bh	SCI12	Control Field 0 Receive Data Register	CF0RR	8	8	2 or 3 PCLKB
0008 B32Ch	SCI12	Primary Control Field 1 Data Register	PCF1DR	8	8	2 or 3 PCLKB
0008 B32Dh	SCI12	Secondary Control Field 1 Data Register	SCF1DR	8	8	2 or 3 PCLKB
0008 B32Eh	SCI12	Control Field 1 Compare Enable Register	CF1CR	8	8	2 or 3 PCLKB
0008 B32Fh	SCI12	Control Field 1 Receive Data Register	CF1RR	8	8	2 or 3 PCLKB
0008 B330h	SCI12	Timer Control Register	TCR	8	8	2 or 3 PCLKB
0008 B331h	SCI12	Timer Mode Register	TMR	8	8	2 or 3 PCLKB
0008 B332h	SCI12	Timer Prescaler Register	TPRE	8	8	2 or 3 PCLKB
0008 B333h	SCI12	Timer Count Register	TCNT	8	8	2 or 3 PCLKB
0008 C000h	PORT0	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C001h	PORT1	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C002h	PORT2	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C003h	PORT3	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C004h	PORT4	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C005h	PORT5	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C00Ah	PORTA	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C00Bh	PORTB	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C00Ch	PORTC	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C00Eh	PORTE	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C012h	PORTJ	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C020h	PORT0	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C021h	PORT1	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C022h	PORT2	Port Output Data Register	PODR	8	8	2 or 3 PCLKB

Table 5.8 DC Characteristics (6) (2/2)Conditions: $1.8\text{ V} \leq \text{VCC} = \text{VCC_USB} \leq 3.6\text{ V}$, $1.8\text{ V} \leq \text{AVSS0} \leq 3.6\text{ V}$, $\text{VSS} = \text{AVSS0} = \text{VSS_USB} = 0\text{ V}$, $T_a = -40\text{ to }+105^\circ\text{C}$

Item					Symbol	Typ *4	Max	Unit	Test Conditions
Supply current*1	Low-speed operating mode	Normal operating mode	No peripheral operation*8	ICLK = 32.768 kHz	I_{CC}	4.3	—	μA	
			All peripheral operation: Normal*9, *10	ICLK = 32.768 kHz		14.7	—		
			All peripheral operation: Max.*9, *10	ICLK = 32.768kHz		—	60		
		Sleep mode	No peripheral operation*8	ICLK = 32.768 kHz		2.2	—		
			All peripheral operation: Normal*9	ICLK = 32.768 kHz		8.3	—		
		Deep sleep mode	No peripheral operation*8	ICLK = 32.768 kHz		1.7	—		
			All peripheral operation: Normal*9	ICLK = 32.768 kHz		6.7	—		

Note 1. Supply current values do not include output charge/discharge current from all pins. The values apply when internal pull-up MOSs are in the off state.

Note 2. Clock supply to the peripheral functions is stopped. This does not include BGO operation. The clock source is PLL. FCLK and PCLK are set to divided by 64.

Note 3. Clocks are supplied to the peripheral functions. This does not include BGO operation. The clock source is PLL. FCLK and PCLK are set to the same frequency as ICLK.

Note 4. Values when $\text{VCC} = 3.3\text{ V}$.

Note 5. This is the increase for programming or erasure of the ROM or E2 DataFlash during program execution.

Note 6. Clock supply to the peripheral functions is stopped. The clock source is PLL when ICLK = 12 MHz, and HOCO otherwise. FCLK and PCLK are set to divided by 64.

Note 7. Clocks are supplied to the peripheral functions. The clock source is PLL when ICLK = 12 MHz, and HOCO otherwise. FCLK and PCLK are set to the same frequency as ICLK.

Note 8. Clock supply to the peripheral functions is stopped. The clock source is the sub-clock oscillator. FCLK and PCLK are set to divided by 64.

Note 9. Clocks are supplied to the peripheral functions. The clock source is the sub-clock oscillator. FCLK and PCLK are set to the same frequency as ICLK.

Note 10. Values when the MSTPCRA.MSTPA17 bit (12-bit A/D converter module stop bit) is set to "transition to the module stop state is made".

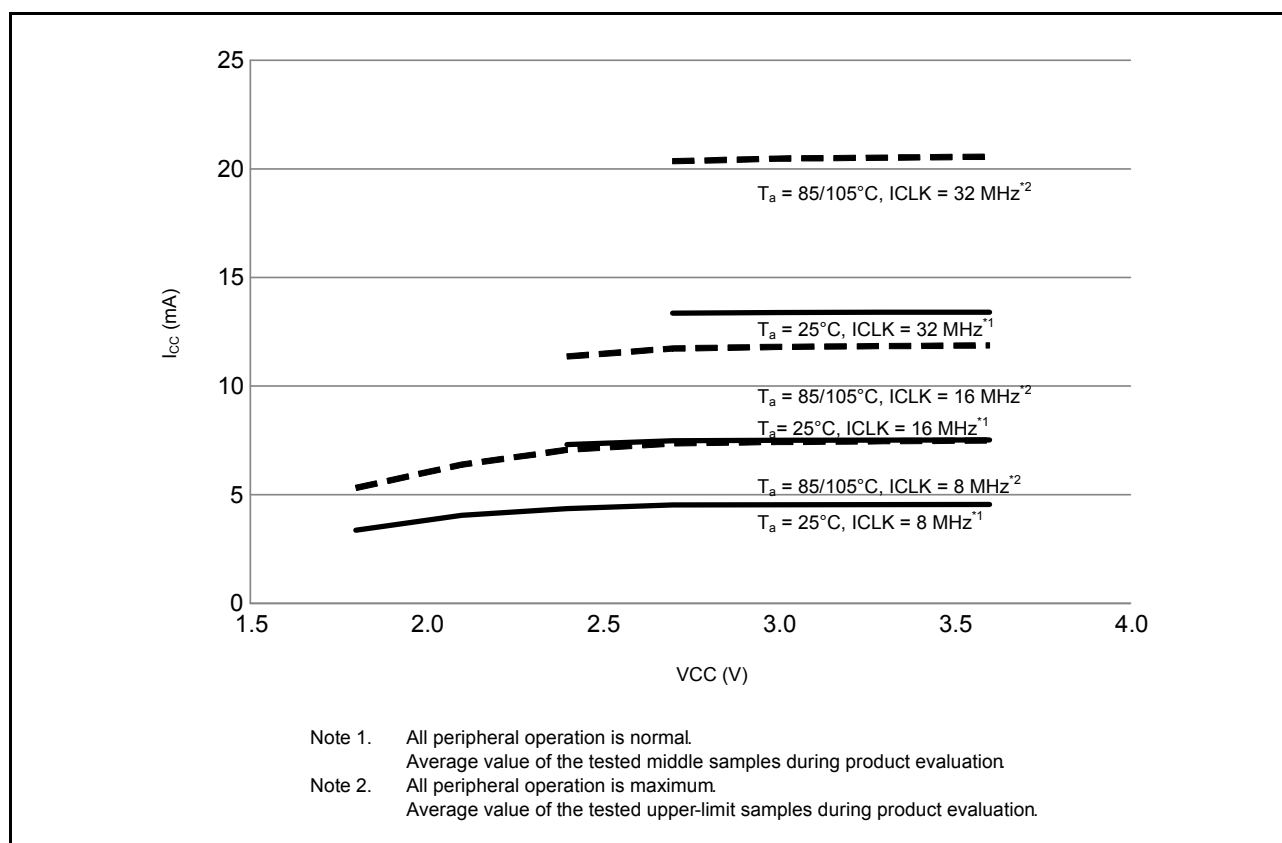


Figure 5.4 Voltage Dependency in High-Speed Operating Mode (Reference Data)

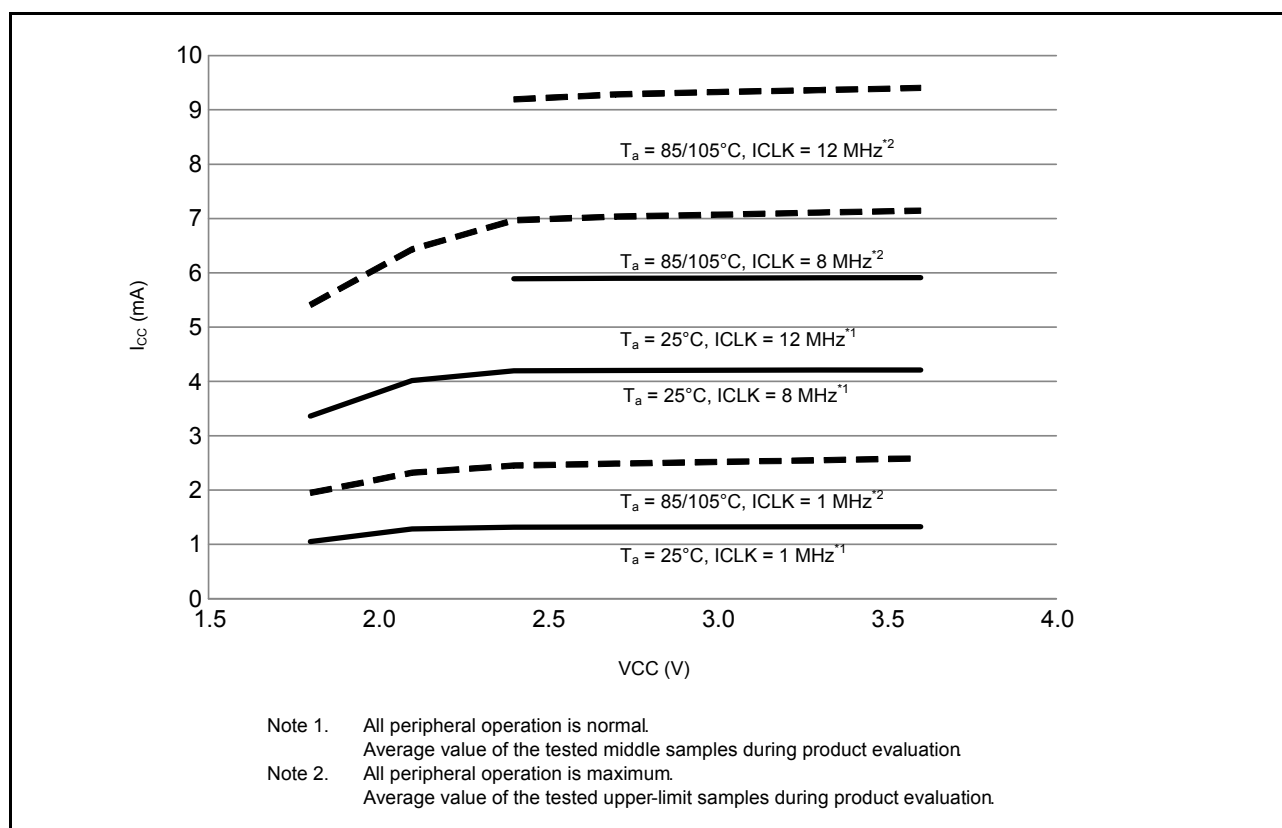


Figure 5.5 Voltage Dependency in Middle-Speed Operating Mode (Reference Data)

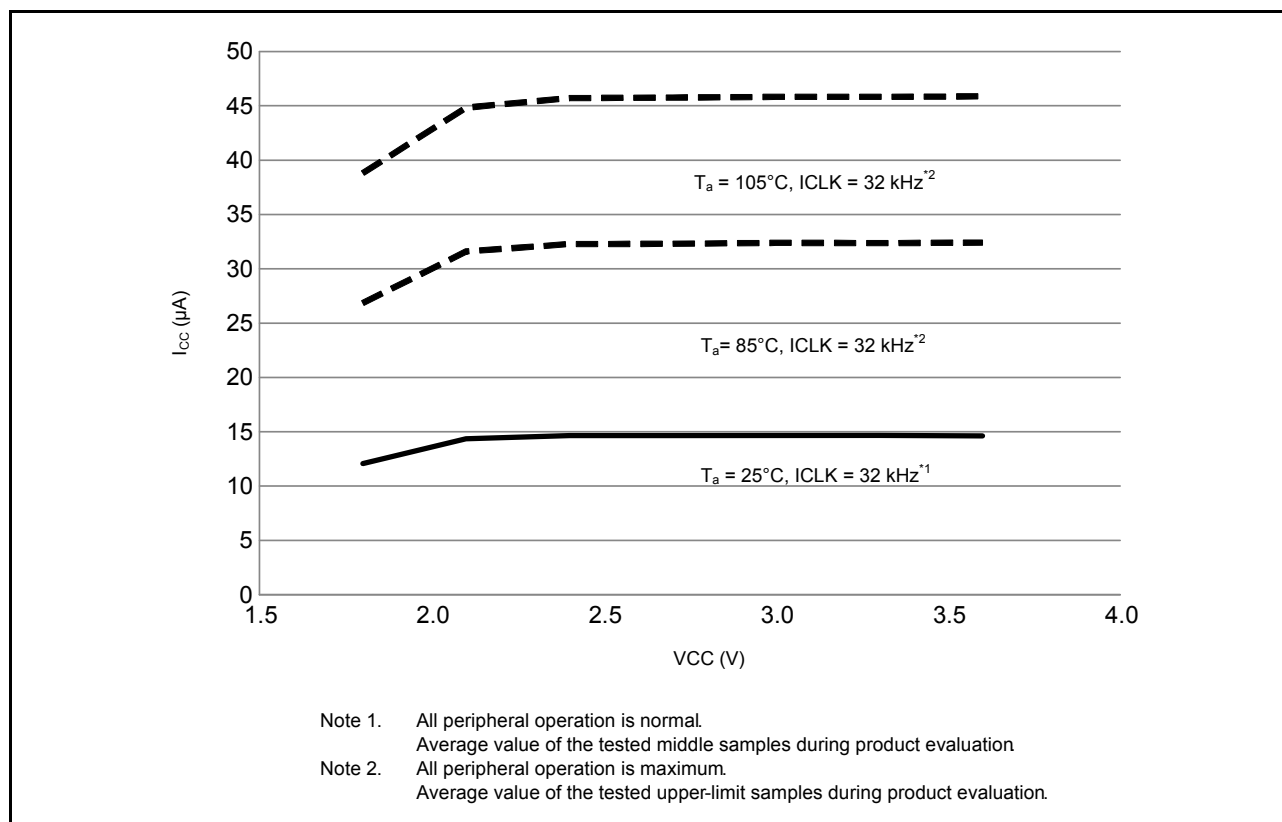


Figure 5.6 Voltage Dependency in Low-Speed Operating Mode (Reference Data)

[128-Kbyte or less flash memory]

Table 5.9 DC Characteristics (7)Conditions: $1.8\text{ V} \leq V_{CC} = V_{CC_USB} \leq 3.6\text{ V}$, $1.8\text{ V} \leq AVSS0 \leq 3.6\text{ V}$, $V_{SS} = AVSS0 = V_{SS_USB} = 0\text{ V}$, $T_a = -40\text{ to }+105^\circ\text{C}$

Item			Symbol	Typ.*3	Max.	Unit	Test Conditions
Supply current*1	Software standby mode*2	$T_a = 25^\circ\text{C}$	I_{CC}	0.35	0.53	μA	
		$T_a = 55^\circ\text{C}$		0.58	1.45		
		$T_a = 85^\circ\text{C}$		1.60	7.30		
		$T_a = 105^\circ\text{C}$		3.30	16.50		
	Increment for RTC operation*4			0.31	—		RCR3.RTCDV[2:0] = 010b
				1.09	—		RCR3.RTCDV[2:0] = 100b
	Increment for IWDG operation			0.37	—		

Note 1. Supply current values do not include output charge/discharge current from all pins. The values apply when internal pull-up MOSs are in the off state.

Note 2. The IWDG and LVD are stopped.

Note 3. $V_{CC} = 3.3\text{ V}$.

Note 4. Includes the oscillation circuit.

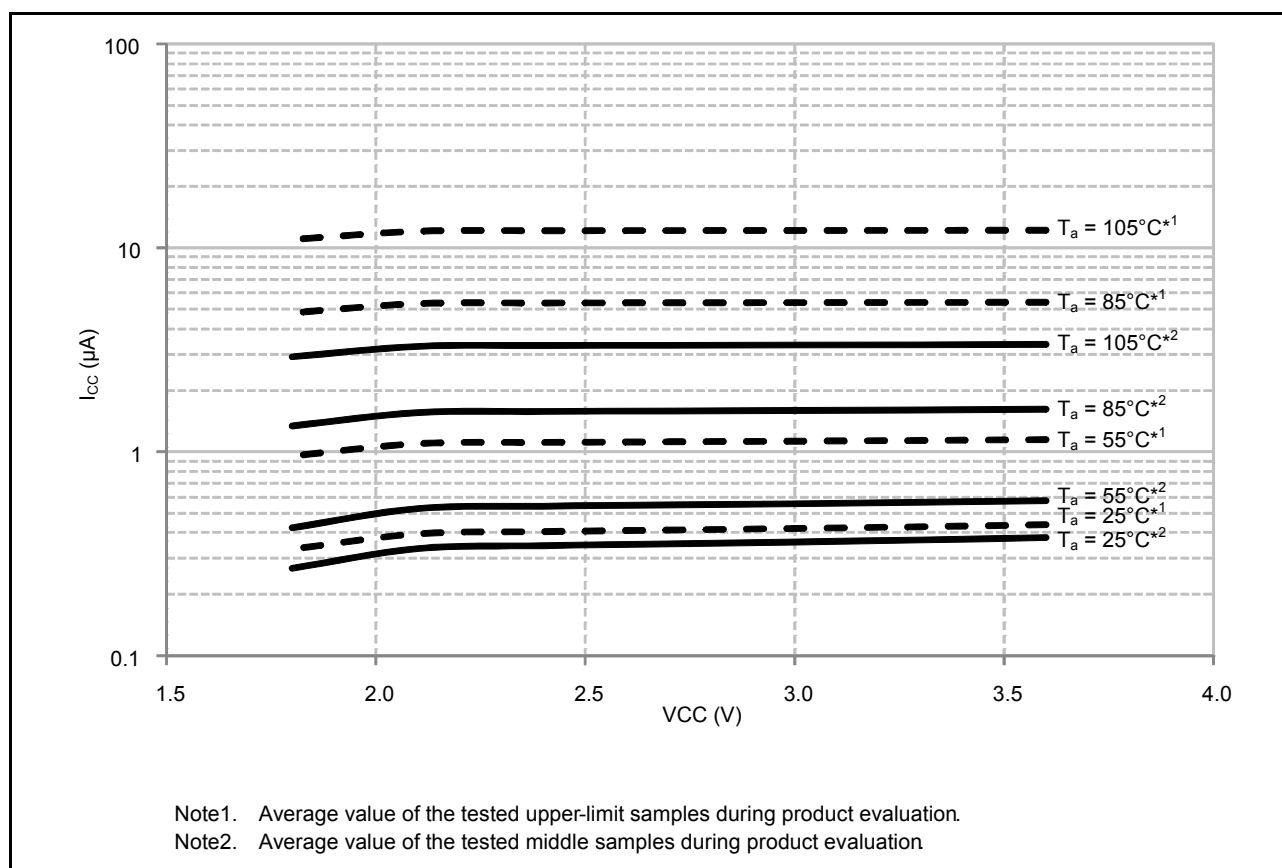
**Figure 5.7 Voltage Dependency in Software Standby Mode (Reference Data)**

Table 5.12 DC Characteristics (10)Conditions: $1.8\text{ V} \leq \text{VCC} = \text{VCC_USB} \leq 3.6\text{ V}$, $1.8\text{ V} \leq \text{AVSS0} \leq 3.6\text{ V}$, $\text{VSS} = \text{AVSS0} = \text{VSS_USB} = 0\text{ V}$, $T_a = -40\text{ to }+105^\circ\text{C}$

Item		Symbol	Min.	Typ.*7	Max.	Unit	Test Conditions
Analog power supply current	During A/D conversion (at high-speed conversion)	I_{AVCC}	—	0.7	1.2	mA	
	Waiting for A/D (all units)		—	—	0.3	μA	
	During D/A conversion (per channel)*5		—	—	1.5	mA	
Reference power supply current	During A/D conversion (at high-speed conversion)	I_{REFH0}	—	25	52	μA	
	Waiting for A/D conversion (all units)		—	—	60	nA	
Temperature sensor*6		I_{TEMP}	—	75	—	μA	
LDV1, 2	Per channel	I_{LVD}	—	0.15	—	μA	
USB operating current	During USB communication operation under the following settings and conditions - Host controller operation is set to full-speed mode - Bulk OUT transfer (64 bytes) × 1, bulk IN transfer (64 bytes) × 1 - Connect peripheral devices via a 1-meter USB cable from the USB port.	I_{USBH}^{*2}	—	4.3 (VCC) 0.9 (VCC_USB) *4	—	mA	
	During USB communication operation under the following settings and conditions - Function controller operation is set to full-speed mode - Bulk OUT transfer (64 bytes) × 1, bulk IN transfer (64 bytes) × 1 - Connect the host device via a 1-meter USB cable from the USB port.	I_{USBF}^{*2}	—	3.6 (VCC) 1.1 (VCC_USB) *4	—	mA	
	During suspended state under the following setting and conditions - Function controller operation is set to full-speed mode (pull up the USB0_DP pin) - Software standby mode - Connect the host device via a 1-meter USB cable from the USB port.	I_{SUSP}^{*3}	—	0.35 (VCC) 170 (VCC_USB) *4	—	μA	

Note 1. The reference power supply current is included in the power supply current value for D/A conversion.

Note 2. Current consumed only by the USB module.

Note 3. Includes the current supplied from the pull-up resistor of the USB0_DP pin to the pull-down resistor of the host device, in addition to the current consumed by this MCU during the suspended state.

Note 4. When $\text{VCC} = \text{VCC_USB} = 3.3\text{ V}$.

Note 5. The value of the current flowing to VCC.

Note 6. Current consumed by the power supply (VCC).

Note 7. When $\text{VCC} = \text{AVCC0} = \text{VCC_USB} = 3.3\text{ V}$.**Table 5.13 DC Characteristics (11)**Conditions: $1.8\text{ V} \leq \text{VCC} = \text{VCC_USB} \leq 3.6\text{ V}$, $1.8\text{ V} \leq \text{AVSS0} \leq 3.6\text{ V}$, $\text{VSS} = \text{AVSS0} = \text{VSS_USB} = 0\text{ V}$, $T_a = -40\text{ to }+105^\circ\text{C}$

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
RAM standby voltage	V_{RAM}	1.8	—	—	V	

Table 5.18 Permissible Output Currents (2)

Conditions: $1.8\text{ V} \leq V_{CC} = V_{CC_USB} \leq 3.6\text{ V}$, $1.8\text{ V} \leq AV_{CC0} \leq 3.6\text{ V}$, $V_{SS} = AV_{SS0} = V_{SS_USB} = 0\text{ V}$,
 $T_a = -40\text{ to }+105^\circ\text{C}$ (G version)

Item		Symbol	Max.	Unit
Permissible output low current (average value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7	I_{OL}	0.4	mA
	Ports other than above		8.0	
Permissible output low current (maximum value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7		0.4	
	Ports other than above		8.0	
Permissible output low current	Total of ports P40 to P44, P46, ports PJ6, PJ7	ΣI_{OL}	1.6	
	Total of ports P03, P05, ports P26, P27, ports P30, P31		20	
	Total of ports P14 to P17, port P32, ports P54, P55, ports PB0, PB1, PB3, PB5 to PB7, ports PC2 to PC7		20	
	Total of ports PA0, PA1, PA3, PA4, PA6, ports PE0 to PE7		20	
	Total of all output pins		40	
Permissible output high current (average value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7	I_{OH}	-0.1	
	Ports other than above		-4.0	
Permissible output high current (maximum value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7		-0.1	
	Ports other than above		-4.0	
Permissible output high current	Total of ports P40 to P44, P46, ports PJ6, PJ7	ΣI_{OH}	-0.6	
	Total of ports P03, P05, ports P26, P27, ports P30, P31		-10	
	Total of ports P14 to P17, port P32, ports P54, P55, ports PB0, PB1, PB3, PB5 to PB7, ports PC2 to PC7		-15	
	Total of ports PA0, PA1, PA3, PA4, PA6, ports PE0 to PE7		-15	
	Total of all output pins		-40	

Note: Do not exceed the permissible total supply current.

Table 5.24 Clock TimingConditions: $1.8\text{ V} \leq \text{VCC} = \text{VCC_USB} \leq 3.6\text{ V}$, $1.8\text{ V} \leq \text{AVSS0} \leq 3.6\text{ V}$, $\text{VSS} = \text{AVSS0} = \text{VSS_USB} = 0\text{ V}$, $T_a = -40\text{ to }+105^\circ\text{C}$

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
XTAL external clock input cycle time	t_{Xcyc}	50	—	—	ns	Figure 5.23
XTAL external clock input high pulse width	t_{XH}	20	—	—	ns	
XTAL external clock input low pulse width	t_{XL}	20	—	—	ns	
XTAL external clock rising time	t_{Xr}	—	—	5	ns	
XTAL external clock falling time	t_{Xf}	—	—	5	ns	
XTAL external clock input wait time*1	t_{EXWT}	0.5	—	—	μs	Figure 5.25
Main clock oscillator oscillation frequency	f_{MAIN}	$2.4 \leq \text{VCC} \leq 3.6$	1	—	20	
		$1.8 \leq \text{VCC} < 2.4$	1	—	8	
Main clock oscillation stabilization time (crystal)*2	t_{MAINOSC}	—	3	—	ms	Figure 5.25
Main clock oscillation stabilization time (ceramic resonator)*2	t_{MAINOSC}	—	50	—	μs	
LOCO clock oscillation frequency	f_{LOCO}	3.44	4.0	4.56	MHz	Figure 5.26
LOCO clock oscillation stabilization time	t_{LOCO}	—	—	0.5	μs	
IWDT-dedicated clock oscillation frequency	f_{ILOCO}	12.75	15	17.25	kHz	Figure 5.24
IWDT-dedicated clock oscillation stabilization time	t_{ILOCO}	—	—	50	μs	
HOCO clock oscillation frequency	f_{HOCO}	31.52	32	32.48	MHz	$T_a = -40\text{ to }85^\circ\text{C}$
		31.68	32	32.32		$T_a = -20\text{ to }85^\circ\text{C}$
		31.36	32	32.64		$T_a = -40\text{ to }105^\circ\text{C}$
HOCO clock oscillation stabilization time	t_{HOCO2}	—	—	56	μs	Figure 5.28
PLL input frequency*3	f_{PLLIN}	4	—	8	MHz	Figure 5.29
PLL circuit oscillation frequency*3	f_{PLL}	32	—	48	MHz	
PLL clock oscillation stabilization time	t_{PLL}	—	—	50	μs	Figure 5.29
PLL free-running oscillation frequency	f_{PLLFR}	—	8	—	MHz	
Sub-clock oscillator oscillation frequency*5	f_{SUB}	—	32.768	—	kHz	Figure 5.30
Sub-clock oscillation stabilization time*4	t_{SUBOSC}	—	0.5	—	s	

Note 1. Time until the clock can be used after the main clock oscillator stop bit (MOSCCR.MOSTP) is set to 0 (operating) when the external clock is stable.

Note 2. Reference values when an 8-MHz oscillator is used.

When specifying the main clock oscillator stabilization time, set the MOSCWTCR register with a stabilization time value that is equal to or greater than the oscillator-manufacturer-recommended value.

After changing the setting of the MOSCCR.MOSTP bit so that the main clock oscillator operates, read the OSCOVFSR.MOOVF flag to confirm that it has become 1, and then start using the main clock.

Note 3. The VCC range that the PLL can be used is 2.4 to 3.6 V.

Note 4. After changing the setting of the SOSCCR.SOSTP bit or RCR3.RTCEN bit so that the sub-clock oscillator operates, only start using the sub-clock after the sub-clock oscillation stabilization wait time that is equal to or greater than the oscillator-manufacturer-recommended value has elapsed.

Reference value when a 32.768-kHz resonator is used.

Note 5. Only 32.768 kHz can be used.

5.3.3 Timing of Recovery from Low Power Consumption Modes

Table 5.26 Timing of Recovery from Low Power Consumption Modes (1)

Conditions: $1.8\text{ V} \leq \text{VCC} = \text{VCC_USB} \leq 3.6\text{ V}$, $1.8\text{ V} \leq \text{AVSS0} \leq 3.6\text{ V}$, $\text{VSS} = \text{AVSS0} = \text{VSS_USB} = 0\text{ V}$, $T_a = -40\text{ to }+105^\circ\text{C}$

Item				Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Recovery time from software standby mode*1	High-speed mode	Crystal connected to main clock oscillator	Main clock oscillator operating*2	t_{SBYMC}	—	2	3	ms	Figure 5.34
			Main clock oscillator and PLL circuit operating*3	t_{SBYPC}	—	2	3	ms	
		External clock input to main clock oscillator	Main clock oscillator operating*4	t_{SBYEX}	—	35	50	μs	
			Main clock oscillator and PLL circuit operating*5	t_{SBYPE}	—	70	95	μs	
		Sub-clock oscillator operating		t_{SBYSC}	—	650	800	μs	
		HOCO clock oscillator operating*6		t_{SBYHO}	—	40	55	μs	
		LOCO clock oscillator operating		t_{SBYLO}	—	40	55	μs	

Note: When the division ratios of PCLKB, PCLKD, FCLK, and ICLK are all set to 1.

Note 1. The recovery time varies depending on the state of each oscillator when the WAIT instruction is executed. The recovery time when multiple oscillators are operating varies depending on the operating state of the oscillators that are not selected as the system clock source. This applies when only the oscillator listed in each item is operating and the other oscillators are stopped.

Note 2. When the frequency of the crystal is 20 MHz.

When the main clock oscillator wait control register (MOSCWTCR) is set to 04h.

Note 3. When the frequency of PLL is 32 MHz.

When the main clock oscillator wait control register (MOSCWTCR) is set to 04h.

Note 4. When the frequency of the external clock is 20 MHz.

When the main clock oscillator wait control register (MOSCWTCR) is set to 00h.

Note 5. When the frequency of PLL is 32 MHz.

When the main clock oscillator wait control register (MOSCWTCR) is set to 00h.

Note 6. When the frequency of HOCO is 32 MHz.

When the high-speed clock oscillator wait control register (HOCOWTCR) is set to 05h.

5.3.4 Control Signal Timing

Table 5.31 Control Signal Timing

Conditions: $1.8\text{ V} \leq \text{VCC} = \text{VCC_USB} \leq 3.6\text{ V}$, $1.8\text{ V} \leq \text{AVSS0} \leq 3.6\text{ V}$, $\text{VSS} = \text{AVSS0} = \text{VSS_USB} = 0\text{ V}$, $T_a = -40\text{ to }+105^\circ\text{C}$

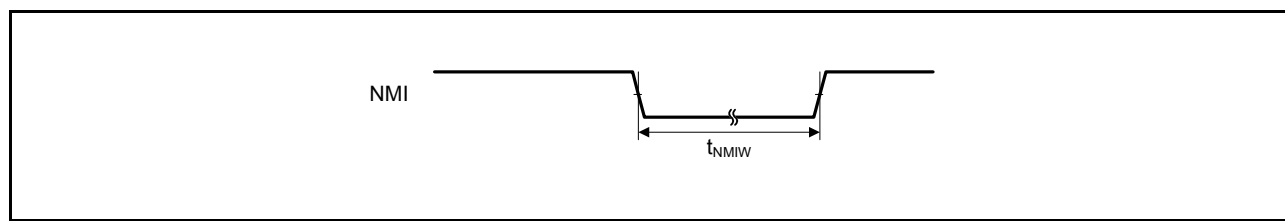
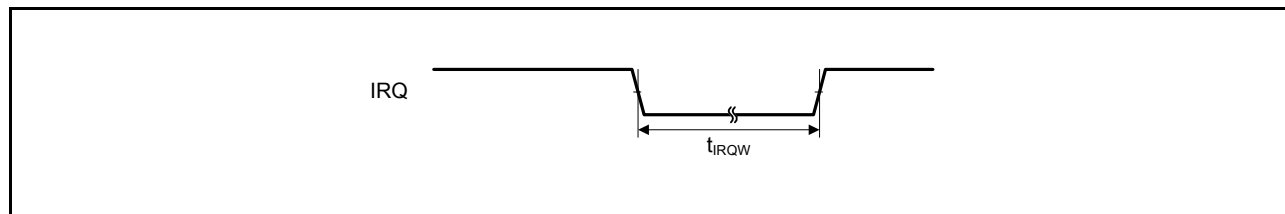
Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions	
NMI pulse width	t_{NMIW}	200	—	—	ns	NMI digital filter disabled (NMIFLTE.NFLTEN = 0)	$t_{\text{Pcyc}} \times 2 \leq 200\text{ ns}$
		$t_{\text{Pcyc}} \times 2^{*1}$	—	—			$t_{\text{Pcyc}} \times 2 > 200\text{ ns}$
		200	—	—		NMI digital filter enabled (NMIFLTE.NFLTEN = 1)	$t_{\text{NMICK}} \times 3 \leq 200\text{ ns}$
		$t_{\text{NMICK}} \times 3.5^{*2}$	—	—			$t_{\text{NMICK}} \times 3 > 200\text{ ns}$
IRQ pulse width	t_{IRQW}	200	—	—	ns	IRQ digital filter disabled (IRQFLTE0.FLTENi = 0)	$t_{\text{Pcyc}} \times 2 \leq 200\text{ ns}$
		$t_{\text{Pcyc}} \times 2^{*1}$	—	—			$t_{\text{Pcyc}} \times 2 > 200\text{ ns}$
		200	—	—		IRQ digital filter enabled (IRQFLTE0.FLTENi = 1)	$t_{\text{IRQCK}} \times 3 \leq 200\text{ ns}$
		$t_{\text{IRQCK}} \times 3.5^{*3}$	—	—			$t_{\text{IRQCK}} \times 3 > 200\text{ ns}$

Note: • 200 ns minimum in software standby mode.

Note 1. t_{Pcyc} indicates the cycle of PCLKB.

Note 2. t_{NMICK} indicates the cycle of the NMI digital filter sampling clock.

Note 3. t_{IRQCK} indicates the cycle of the IRQi digital filter sampling clock (i = 0 to 7).

**Figure 5.36 NMI Interrupt Input Timing****Figure 5.37 IRQ Interrupt Input Timing**

5.3.5 Timing of On-Chip Peripheral Modules

Table 5.32 Timing of On-Chip Peripheral Modules (1)Conditions: $1.8\text{ V} \leq \text{VCC} = \text{VCC_USB} \leq 3.6\text{ V}$, $1.8\text{ V} \leq \text{AVSS0} \leq 3.6\text{ V}$, $\text{VSS} = \text{AVSS0} = \text{VSS_USB} = 0\text{ V}$, $T_a = -40\text{ to }+105^\circ\text{C}$

Item				Symbol	Min.	Max.	Unit*1	Test Conditions
I/O ports	Input data pulse width			t _{PRW}	1.5	—	t _{PCYC}	Figure 5.38
MTU2	Input capture input pulse width	Single-edge setting	t _{TICW}	1.5	—	t _{PCYC}	Figure 5.39	
		Both-edge setting		2.5	—			
	Timer clock pulse width	Single-edge setting	t _{TCKWH} , t _{TCKWL}	1.5	—	t _{PCYC}	Figure 5.40	
		Both-edge setting		2.5	—			
		Phase counting mode		2.5	—			
POE	POE# input pulse width			t _{POEW}	1.5	—	t _{PCYC}	Figure 5.41
SCI	Input clock cycle	Asynchronous	t _{SCYC}	4	—	t _{PCYC}	Figure 5.42	
		Clock synchronous		6	—			
	Input clock pulse width			t _{SCKW}	0.4	0.6	t _{SCYC}	Figure 5.43 C = 30 pF
	Input clock rise time			t _{SCKr}	—	20	ns	
	Input clock fall time			t _{SCKf}	—	20	ns	
	Output clock cycle	Asynchronous	t _{SCYC}	16	—	t _{PCYC}		
		Clock synchronous		4	—			
	Output clock pulse width			t _{SCKW}	0.4	0.6	t _{SCYC}	
	Output clock rise time			t _{SCKr}	—	20	ns	
	Output clock fall time			t _{SCKf}	—	20	ns	
	Transmit data delay time (master)	Clock synchronous		t _{TXD}	—	40	ns	
	Transmit data delay time (slave)	Clock synchronous	2.7 V or above		—	65	ns	
			1.8 V or above		—	100	ns	
	Receive data setup time (master)	Clock synchronous	2.7 V or above	t _{RXS}	65	—	ns	
			1.8 V or above		90	—	ns	
	Receive data setup time (slave)	Clock synchronous			40	—	ns	
	Receive data hold time	Clock synchronous		t _{RXH}	40	—	ns	
A/D converter	Trigger input pulse width			t _{TRGW}	1.5	—	t _{PCYC}	Figure 5.44
CAC	CACREF input pulse width	t _{PCYC} ≤ t _{CAC} *2	t _{CACREF}	4.5 t _{CAC} + 3 t _{PCYC}	—	ns		
		t _{PCYC} > t _{CAC} *2		5 t _{CAC} + 6.5 t _{PCYC}				
CLKOUT	CLKOUT pin output cycle*4	VCC = 2.7 V or above	t _{CCYC}	125	—	ns		
		VCC = 1.8 V or above		250				
	CLKOUT pin high pulse width*3	VCC = 2.7 V or above	t _{CH}	35	—	ns		
		VCC = 1.8 V or above		70				
	CLKOUT pin low pulse width*3	VCC = 2.7 V or above	t _{CL}	35	—	ns		
		VCC = 1.8 V or above		70				
	CLKOUT pin output rise time	VCC = 2.7 V or above	t _{Cr}	—	15	ns		
		VCC = 1.8 V or above		30				
	CLKOUT pin output fall time	VCC = 2.7 V or above	t _{Cf}	—	15	ns		
		VCC = 1.8 V or above		30				

Note 1. t_{Pcyc} : PCLK cycleNote 2. t_{cac} : CAC count clock source cycle

Note 3. When the LOCO is selected as the clock output source (CKOCR.CKOSEL[2:0] bits = 000b), set the clock output division ratio selection to divided by 2 (CKOCR.CKODIV[2:0] bits = 001b).

Note 4. When the XTAL external clock input or an oscillator is used with divided by 1 (CKOCR.CKOSEL[2:0] bits = 010b and CKOCR.CKODIV[2:0] bits = 000b) to output from CLKOUT, the above should be satisfied with an input duty cycle of 45 to 55%.

5.5 A/D Conversion Characteristics

Table 5.38 A/D Conversion Characteristics (1)

Conditions: $2.7\text{ V} \leq VCC = VCC_USB \leq 3.6\text{ V}$, $2.7\text{ V} \leq AVCC0 \leq 3.6\text{ V}$, $2.7\text{ V} \leq VREFH0 \leq AVCC0$,
 $VSS = AVSS0 = VREFL0 = VSS_USB = 0\text{ V}$, $T_a = -40\text{ to }+105^\circ\text{C}$

Item		Min.	Typ.	Max.	Unit	Test Conditions
Frequency		4	—	32	MHz	
Resolution		—	—	12	Bit	
Conversion time*1 (Operation at PCLKD = 32 MHz)	Permissible signal source impedance (Max.) = 0.3 kΩ	1.031 (0.313)*2	—	—	μs	High-precision channel ADCSR.ADHSC bit = 1 ADSSTRn.SST[7:0] bits = 09h
		1.375 (0.641)*2	—	—		Normal-precision channel ADCSR.ADHSC bit = 1 ADSSTRn.SST[7:0] bits = 14h
Analog input effective range		0	—	VREFH0	V	
Offset error		—	±0.5	±4.5	LSB	High-precision channel PJ6PFS.ASEL bit = 1 PJ7PFS.ASEL bit = 1
				±6.0	LSB	Other than above
Full-scale error		—	±0.75	±4.5	LSB	High-precision channel PJ6PFS.ASEL bit = 1 PJ7PFS.ASEL bit = 1
				±6.0	LSB	Other than above
Quantization error		—	±0.5	—	LSB	
Absolute accuracy		—	±1.25	±5.0	LSB	High-precision channel PJ6PFS.ASEL bit = 1 PJ7PFS.ASEL bit = 1
				±8.0	LSB	Other than above
DNL differential nonlinearity error		—	±1.0	—	LSB	
INL integral nonlinearity error		—	±1.0	±3.0	LSB	

Note: • The characteristics apply when no pin functions other than A/D converter input are used. Absolute accuracy includes quantization errors. Offset error, full-scale error, DNL differential nonlinearity error, and INL integral nonlinearity error do not include quantization errors.

Note 1. The conversion time is the sum of the sampling time and the comparison time. As the test conditions, the number of sampling states is indicated.

Note 2. The value in parentheses indicates the sampling time.

Table 5.41 A/D Converter Channel Classification

Classification	Channel	Conditions	Remarks
High-precision channel	AN000 to AN004, AN006	AVCC0 = 1.8 to 3.6 V	Pins AN000 to AN004 and AN006 cannot be used as digital outputs when the A/D converter is in use.
Normal-precision channel	AN008 to AN015		
Internal reference voltage input channel	Internal reference voltage	AVCC0 = 2.0 to 3.6 V	
Temperature sensor input channel	Temperature sensor output	AVCC0 = 2.0 to 3.6 V	

Table 5.42 A/D Internal Reference Voltage Characteristics

Conditions: $2.0\text{ V} \leq VCC = VCC_USB \leq 3.6\text{ V}$, $2.0\text{ V} \leq AVCC0 \leq 3.6\text{ V}^{*1}$, $VSS = AVSS0 = VREFL0 = VSS_USB = 0\text{ V}$, $T_a = -40$ to $+105^\circ\text{C}$

Item	Min.	Typ.	Max.	Unit	Test Conditions
Internal reference voltage input channel*2	1.36	1.43	1.50	V	

Note 1. The internal reference voltage cannot be selected for input channels when $AVCC0 < 2.0\text{ V}$.

Note 2. The A/D internal reference voltage indicates the voltage when the internal reference voltage is input to the A/D converter.

5.11 E2 DataFlash Characteristics

Table 5.51 E2 DataFlash Characteristics (1)

Item		Symbol	Min.	Typ.	Max.	Unit	Conditions
Reprogramming/erasure cycle*1		N _{DPEC}	100000	1000000	—	Times	
Data hold time	After 10000 times of N _{DPEC}	t _{DDRP}	20*2, *3	—	—	Year	Ta = +85°C
	After 100000 times of N _{DPEC}		5*2, *3	—	—	Year	
	After 1000000 times of N _{DPEC}		—	1*2, *3	—	Year	Ta = +25°C

Note 1. The reprogram/erase cycle is the number of erasing for each block. When the reprogram/erase cycle is n times (n = 100000), erasing can be performed n times for each block. For instance, when 1-byte programming is performed 1000 times for different addresses in 1-byte block and then the entire block is erased, the reprogram/erase cycle is counted as one. However, programming the same address for several times as one erasing is not enabled (overwriting is prohibited).

Note 2. Characteristics when using the flash memory programmer and the self-programming library provided from Renesas Electronics.

Note 3. These results are obtained from reliability testing.

**Table 5.52 E2 DataFlash Characteristics (2)
: high-speed operating mode**

Conditions: 2.7 V ≤ VCC ≤ 3.6 V, 2.7 V ≤ AVSS0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V

Temperature range for the programming/erasure operation: Ta = −40 to +105°C

Item		Symbol	FCLK = 1 MHz			FCLK = 32 MHz			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	
Programming time	1-byte	t _{DP1}	—	86	761	—	40.5	374	μs
Erasure time	1-Kbyte	t _{DE1K}	—	17.4	456	—	6.15	228	ms
	8-Kbyte	t _{DE8K}	—	60.4	499	—	9.3	231	ms
Blank check time	1-byte	t _{DBC1}	—	—	48	—	—	15.9	μs
	1-Kbyte	t _{DBC1K}	—	—	1.58	—	—	0.127	μs
Erase operation forcible stop time		t _{DSER}	—	—	21.5	—	—	12.8	μs
DataFlash STOP recovery time		t _{DSTOP}	5	—	—	5	—	—	μs

Note: • Does not include the time until each operation of the flash memory is started after instructions are executed by software.

Note: • The lower-limit frequency of FCLK is 1 MHz during programming or erasing of the flash memory. When using FCLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.

Note: • The frequency accuracy of FCLK should be ±3.5%. Confirm the frequency accuracy of the clock source.

**Table 5.53 E2 DataFlash Characteristics (3)
: middle-speed operating mode**

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVSS0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V

Temperature range for the programming/erasure operation: Ta = −40 to +85°C

Item		Symbol	FCLK = 1 MHz			FCLK = 8 MHz			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	
Programming time	1-byte	t _{DP1}	—	126	1160	—	85.4	818	μs
Erasure time	1-Kbyte	t _{DE1K}	—	17.5	457	—	7.76	259	ms
	8-Kbyte	t _{DE8K}	—	60.5	500	—	16.7	267.6	ms
Blank check time	1-byte	t _{DBC1}	—	—	78	—	—	50	μs
	1-Kbyte	t _{DBC1K}	—	—	1.61	—	—	0.369	ms
Erase operation forcible stop time		t _{DSER}	—	—	33.5	—	—	25.5	μs
DataFlash STOP recovery time		t _{DSTOP}	720	—	—	720	—	—	ns

Note: • Does not include the time until each operation of the flash memory is started after instructions are executed by software.

Note: • The lower-limit frequency of FCLK is 1 MHz during programming or erasing of the flash memory. When using FCLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.

Note: • The frequency accuracy of FCLK should be ±3.5%. Confirm the frequency accuracy of the clock source.

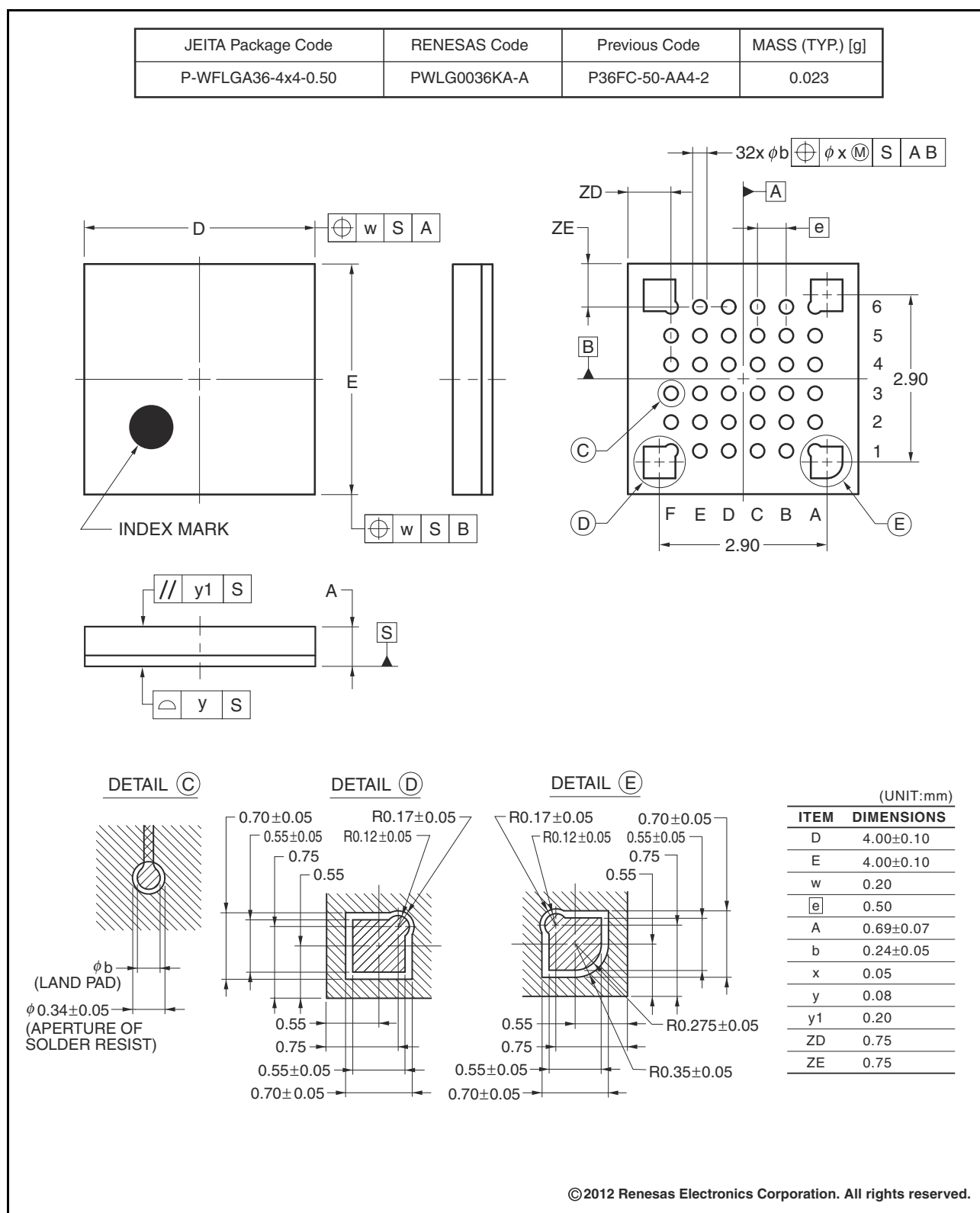


Figure G 36-Pin WFLGA (PWLG0036KA-A)